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- Meets or Exceeds the Requirements of ANSI TIA/EIA-644-1995 Standard
- Signaling Rates up to 400 Mbit/s
- Bus-Terminal ESD Exceeds 12 kV
- Operates from a Single 3.3-V Supply
- Low-Voltage Differential Signaling with Typical Output Voltages of 350 mV and a 100 Ω Load
- Propagation Delay Times
 Driver: 1.7 ns Typ
 - Receiver: 3.7 ns Typ
- Power Dissipation at 200 MHz
 - Driver: 25 mW Typical
 - Receiver: 60 mW Typical
- LVTTL Input Levels are 5 V Tolerant
- Driver is High Impedance When Disabled or With V_{CC} < 1.5 V
- Receiver has Open-Circuit Fail Safe
- Surface-Mount Packaging
 D Package (SOIC)
 - DGK Package (MSOP) ('LVDS179 Only)

description

The SN65LVDS179, SN65LVDS180, SN65LVDS050, and SN65LVDS051 are differential line drivers and receivers that use low-voltage differential signaling (LVDS) to achieve signaling rates as high as 400 Mbps. The TIA/EIA-644 standard compliant electrical interface provides a minimum differential output voltage magnitude of 247 mV into a 100 Ω load and receipt of 100 mV signals with up to 1 V of ground potential difference between a transmitter and receiver.

The intended application of this device and signaling technique is for point-to-point baseband data transmission over controlled impedance media of approximately 100 Ω characteristic impedance. The transmission media may be printed-circuit board traces, backplanes, or cables. (Note: The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media, the noise coupling to the environment, and other application specific characteristics).



SN65LVDS180 . . . D PACKAGE (TOP VIEW)

NC [• 1	14]v _{cc}
_ R [2	13	Vcc
RE [3	12] A
DE [4	11]в
D [5	10] Z
GND [6	9] Y
GND [7	8] NC



8

7

SN65LVDS	050	. D PAC	KAGE
(TOP VI	EW)	
Г	•		

1B [• 1	16]v _{cc}
1A [2	15] 1D
1R [3	14] 1Y
RE [4	13] 1Z
2R [5	12] DE
2A [6	11] 2Z
2B [7	10] 2Y
GND [8	9] 2D









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description (continued)

	PACKAGE		
Τ _Α	SMALL OUTLINE (D)	SMALL OUTLINE (DGK)	
-40°C to 85°C	SN65LVDS050D	—	
	SN65LVDS051D	—	
	SN65LVDS179D	SN65LVDS179DGK	
	SN65LVDS180D	_	

AVAILABLE OPTIONS

NOTE:

The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media, the noise coupling to the environment, and other application specific characteristics.

The SN65LVDS179, SN65LVDS180, SN65LVDS050, and SN65LVDS051 are characterized for operation from -40°C to 85°C.

Function Tables

INPUTS	OUTPUT
$V_{ID} = V_A - V_B$	R
V _{ID} ≥ 100 mV	Н
–100 MV < V _{ID} < 100 mV	?
$V_{ID} \le -100 \text{ mV}$	L
Open	Н

H = high level, L = low level, ? = indeterminate

SN65LVDS179 DRIVER

INPUT	OUTPUTS		
D	Y	Z	
L	L	Н	
Н	Н	L	
Open	L	Н	
H - high lovel I - low lovel			

H = high level, L = low level

SN65LVDS180, SN65LVDS050, and SN65LVDS051 RECEIVER

INPUTS		OUTPUT
$V_{ID} = V_A - V_B$	RE	R
$V_{ID} \ge 100 \text{ mV}$	L	Н
–100 MV < V _{ID} < 100 mV	L	?
$V_{ID} \le -100 \text{ mV}$	L	L
Open	L	Н
Х	н	Z

H = high level, L = low level, Z = high impedance, X = don't care



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SN65LVDS051 DRIVER				
INPUTS		OUTPUTS		
D	DE	Y	Z	
L	Н	L	Н	
Н	Н	Н	L	
Open	Н	L	Н	
Х	L	Z	Z	

SN65LVDS180, SN65LVDS050, and

H = high level, L = low level, Z = high impedance,

X = don't care

equivalent input and output schematic diagrams





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absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage range, V _{CC} (see Note 1)	
Voltage range (D, R, DE, RE)	0.5 V to 6 V
Electrostatic discharge: Y, Z, A, B , and GND (see Note 2)	CLass 3, A:12 kV, B:600 V
All	Class 3, A:7 kV, B:500 V
Continuous power dissipation	see dissipation rating table
Storage temperature range	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	250°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential I/O bus voltages are with respect to network ground terminal.

2. Tested in accordance with MIL-STD-883C Method 3015.7.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C [†]	T _A = 85°C POWER RATING
D8	725 mW	5.8 mW/°C	377 mW
D14 or D16	950 mW	7.8 mW/°C	494 mW
DGK	424 mW	3.4 mW/°C	220 mW

[†]This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

recommended operating conditions

	MIN	NOM MAX	UNIT
Supply voltage, V _{CC}	3	3.3 3.6	V
High-level input voltage, V _{IH}	2		V
Low-level input voltage, VIL		0.8	V
Magnitude of differential input voltage, VID	0.1	0.6	V
Common-mode input voltage, V _{IC} (see Figure 6)	$\frac{\left V_{\text{ID}}\right }{2}$	$2.4 - \frac{ V_{ID} }{2}$	V
		V _{CC} -0.8	
Operating free–air temperature, T _A	-40	85	°C



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device electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
		SN65LVDS179	No receiver load, Driver $R_L = 100 \Omega$		9	12	mA
		SN65LVDS180	Driver and receiver enabled, No receiver load, Driver R_L = 100 Ω		9	12	mA
			Driver enabled, Receiver disabled, RL = 100 Ω		5	7	
			Driver disabled, Receiver enabled, No load		1.5	2	
ICC		Disabled		0.5	1		
	Supply current Drivers and receivers enabled, No receiver loads, Driver $R_L = 100 \Omega$ SN65LVDS050 Drivers enabled, Receivers disabled, $R_L = 100 \Omega$ Drivers disabled, Receivers disabled, $R_L = 100 \Omega$ Drivers disabled, Receivers enabled, No loads Disabled Drivers enabled, No receiver loads, Driver $R_L = 100 \Omega$	Supply current		Drivers and receivers enabled, No receiver loads, Driver RL = 100 Ω		12	20
		SN65LVDS050	Drivers enabled, Receivers disabled, RL = 100 Ω		10	16	mA
			Drivers disabled, Receivers enabled, No loads		3	6	
		Disabled		0.5	1		
			Drivers enabled, No receiver loads, Driver RL = 100 Ω		12	20	٣٨
		3N03LVD3031	Drivers disabled, No loads		3	6	ША

[†] All typical values are at 25°C and with a 3.3-V supply.

driver electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{OD}	D Differential output voltage magnitude		PL - 1000	247	340	454	mV
$\Delta V_{OD} $	Change in differential output voltage magnitude between logic states		See Figure 1 and Figure 2	-50		50	
VOC(SS)	Steady-state common-mode output voltage			1.125	1.2	1.375	V
ΔVOC(SS)	ΔVOC(SS) Change in steady-state common-mode output voltage between logic states		See Figure 3	-50		50	mV
V _{OC(PP)} Peak-to-peak common-mode output voltage				50	150	mV	
	High-level input current	DE	V _{IH} = 5 V		-0.5	-20	μA
ЧН		D			2	20	
i	Low-level input current	DE	V _{IL} = 0.8 V		-0.5	-10	μΑ
'IL		D			2	10	
	Short circuit output current		VOA or $AOZ = 0$ A		3	10	m /
IOS Short-circuit output current		$V_{OD} = 0 V$		3	10	IIIA	
107	High-impedance output current		V _{OD} = 600 mV			±1	uА
102			$V_{O} = 0 V \text{ or } V_{CC}$			±1	μΛ
IO(OFF)	D(OFF) Power-off output current		$V_{CC} = 0 V, V_{O} = 3.6 V$			±1	μA
CIN Input capacitance				3		pF	



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receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
VITH+ Positive-going differential input voltage threshold		See Figure 5 and Table 1			100	m\/
VITH-	Negative-going differential input voltage threshold	See Figure 5 and Table 1				IIIV
VOH	High-level output voltage	I _{OH} = -8 mA	2.4			V
V _{OL}	Low-level output voltage	I _{OL} = 8 mA			0.4	V
łı	Input current (A or B inputs) $ \begin{array}{c} V_{I} = 0 \\ \\ V_{I} = 2.4 \ V \end{array} $	-2	-11	-20	۸	
		V _I = 2.4 V	-1.2	-3		μΑ
I _{I(OFF)}	Power-off input current (A or B inputs)	$V_{CC} = 0$			±20	μΑ
I _{IH}	High-level input current (enables)	V _{IH} = 5 V			±10	μΑ
۱ _{IL}	Low-level input current (enables)	V _{IL} = 0.8 V			±10	μA
I _{OZ}	High-impedance output current	$V_{O} = 0 \text{ or } 5 V$			±10	μA
Cl	Input capacitance			5		pF

[†] All typical values are at 25°C and with a 3.3-V supply.

driver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
^t PLH	Propagation delay time, low-to-high-level output			1.7	2.7	ns
^t PHL	Propagation delay time, high-to-low-level output			1.7	2.7	ns
t _r	Differential output signal rise time	$R_L = 100\Omega$,		0.8	1	ns
t _f	Differential output signal fall time	See Figure 6		0.8	1	ns
t _{sk(p)}	Pulse skew (t _{pHL} – t _{pLH})	<u>j</u>		300		ps
^t sk(o)	Channel-to-channel output skew‡			150		ps
^t PZH	Propagation delay time, high-impedance-to-high-level output			4.3	10	ns
tPZL Propagation delay time, high-impedance-to-low-level output				4.6	10	ns
^t PHZ	Propagation delay time, high-level-to-high-impedance output	3.1 3.4		3.1	10	ns
t _{pLZ}	Propagation delay time, low-level-to-high-impedance output			10	ns	

[†] All typical values are at 25°C and with a 3.3-V supply.

 $t_{sk(0)}$ is the maximum delay time difference between drivers on the same device.



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receiver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
^t PLH	Propagation delay time, low-to-high-level output			3.7	4.5	ns
^t PHL	Propagation delay time, high-to-low-level output			3.7	4.5	ns
t _{sk(p)}	Pulse skew (t _{pHL} – t _{pLH})	CL = 10 pF, See Figure 6		0.3		ns
t _r	Output signal rise time	ooo rigaro o		0.7	1.5	ns
t _f	Output signal fall time			0.9	1.5	ns
^t PZH	Propagation delay time, high-level-to-high-impedance output			2.5		ns
tPZL Propagation delay time, low-level-to-low-impedance output		Soo Eiguro 7		2.5		ns
^t PHZ	Propagation delay time, high-impedance-to-high-level output	See Figure 7		7		ns
^t PLZ	Propagation delay time, low-impedance-to-high-level output	4				ns

 † All typical values are at 25°C and with a 3.3-V supply.

PARAMETER MEASUREMENT INFORMATION

driver



Figure 1. Driver Voltage and Current Definitions



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driver (continued)



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns . CL includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.





NOTE A: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10±0.2 ns. CL includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T. The measurement of $V_{OC(PP)}$ is made on test equipment with a –3 dB bandwidth of at least 300 MHz.

Figure 3. Test Circuit and Definitions for the Driver Common-Mode Output Voltage



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PARAMETER MEASUREMENT INFORMATION

driver (continued)



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \le 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns . C_1 includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.

Figure 4. Enable and Disable Time Circuit and Definitions



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PARAMETER MEASUREMENT INFORMATION

receiver



Figure 5. Receiver Voltage Definitions

APPLIED VOLTAGES (V)		RESULTING DIFFERENTIAL INPUT VOLTAGE (mV)	RESULTING COMMON- MODE INPUT VOLTAGE (V)			
VIA	VIB	V _{ID}	V _{IC}			
1.25	1.15	100	1.2			
1.15	1.25	-100	1.2			
2.4	2.3	100	2.35			
2.3	2.4	-100	2.35			
0.1	0	100	0.05			
0	0.1	-100	0.05			
1.5	0.9	600	1.2			
0.9	1.5	-600	1.2			
2.4	1.8	600	2.1			
1.8	2.4	-600	2.1			
0.6	0	600	0.3			
0	0.6	-600	0.3			

Table 1. Receiver Minimum and Maximum Input Threshold Test Voltages



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PARAMETER MEASUREMENT INFORMATION



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_{f} or $t_{f} \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns. CL includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

Figure 6. Timing Test Circuit and Waveforms



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PARAMETER MEASUREMENT INFORMATION

receiver (continued)



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_f or $t_f \le 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns. C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.





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TYPICAL CHARACTERISTICS









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TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS



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APPLICATION INFORMATION

The devices are generally used as building blocks for high-speed point-to-point data transmission. Ground differences are less than 1 V with a low common-mode output and balanced interface for very low noise emissions. Devices can interoperate with RS-422, PECL, and IEEE-P1596. Drivers/Receivers maintain ECL speeds without the power and dual supply requirements.



Figure 17. Data Transmission Distance Versus Rate



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APPLICATION INFORMATION

fail safe

One of the most common problems with differential signaling applications is how the system responds when no differential voltage is present on the signal pair. The LVDS receiver is like most differential line receivers, in that its output logic state can be indeterminate when the differential input voltage is between –100 mV and 100 mV and within its recommended input common-mode voltage range. TI's LVDS receiver is different in how it handles the open-input circuit situation, however.

Open-circuit means that there is little or no input current to the receiver from the data line itself. This could be when the driver is in a high-impedance state or the cable is disconnected. When this occurs, the LVDS receiver will pull each line of the signal pair to near V_{CC} through 300-k Ω resistors as shown in Figure 11. The fail-safe feature uses an AND gate with input voltage thresholds at about 2.3 V to detect this condition and force the output to a high-level regardless of the differential input voltage.



Figure 18. Open-Circuit Fail Safe of the LVDS Receiver

It is only under these conditions that the output of the receiver will be valid with less than a 100-mV differential input voltage magnitude. The presence of the termination resistor, Rt, does not affect the fail-safe function as long as it is connected as shown in the figure. Other termination circuits may allow a dc current to ground that could defeat the pull-up currents from the receiver and the fail-safe feature.



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MECHANICAL DATA

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012



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MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

DGK (R-PDSO-G8)

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-187



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